

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6633148

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIWAN KIM	03/30/2021
YONGWOO LEE	03/30/2021
SEONGYONG UHM	03/30/2021
SUNGWOOK KO	03/30/2021
UIHYEON JEONG	03/30/2021
RECEIVING PARTY DATA	
Name:	LG DISPLAY CO., LTD.
Street Address:	128, YEOUI-DAERO, YEONGDEUNGPO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	07336
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17218605
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	ROBERT J. GOODELL
Address Line 1:	MORGAN, LEWIS & BOCKIUS LLP
Address Line 2:	1111 PENNSYLVANIA AVE, NW
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ATTORNEY DOCKET NUMBER:	002463-5353
NAME OF SUBMITTER:	ROBERT J. GOODELL
SIGNATURE:	/Robert J. Goodell/
DATE SIGNED:	03/31/2021
Total Attachments: 4	

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source=002463-5353-US_CombDecAssign#page4.tif

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name):	Chiwan KIM
Signature:	Date:
NAME OF INVENTOR (Full Legal Name):	YongWoo LEE
Signature: YongWoo LEE	Date: 30.03.21
NAME OF INVENTOR (Full Legal Name):	SeongYong UHM
Signature:	Date:
NAME OF INVENTOR (Full Legal Name):	Sungwook KO
Signature: Sungwook Ko	Date: 30.03.21
NAME OF INVENTOR (Full Legal Name):	Uihyeon JEONG
Signature: Uihyeon Jeong	Date: 30.03.21
NAME OF INVENTOR (Full Legal Name):	
Signature:	Date:

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NAME OF INVENTOR (Full Legal Name) : Chiwan KIM

Signature: Chiwan KIM Date: 03.30.2021

NAME OF INVENTOR (Full Legal Name) : YongWoo LEE

Signature: _____ Date: _____

NAME OF INVENTOR (Full Legal Name) : SeongYong UHM

Signature: _____ Date: _____

NAME OF INVENTOR (Full Legal Name) : Sungwook KO

Signature: _____ Date: _____

NAME OF INVENTOR (Full Legal Name) : Uihyeon JEONG

Signature: _____ Date: _____

NAME OF INVENTOR (Full Legal Name) : _____

Signature: _____ Date: _____



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NAME OF INVENTOR (Full Legal Name) : Chiwan KIM

Signature: _____ Date: _____

NAME OF INVENTOR (Full Legal Name) : YangWoo LEE

Signature: _____ Date: _____

NAME OF INVENTOR (Full Legal Name) : SeongYong UHM

Signature: Seong Yong UHM Date: 30 March 21

NAME OF INVENTOR (Full Legal Name) : Sungwook KO

Signature: _____ Date: _____

NAME OF INVENTOR (Full Legal Name) : Uihyeon JEONG

Signature: _____ Date: _____

NAME OF INVENTOR (Full Legal Name) : _____

Signature: _____ Date: _____

